

# PC3H4/PC3Q64Q

**Mini-falt Package AC Input Type  
Half Pitch Photocoupler**

## ■ Features

1. AC input type
  2. Half pitch type (lead pitch : 1.27mm)
  3. Isolation voltage between input and output  
(Viso: 2 500Vrms)
  4. Applicable to infrared ray reflow  
(230°C, for MAX. 30s)
  5. High reliability
  6. Taping package
- PC3H4** (1ch), **PC3Q64Q** (4ch)
7. Recognized by UL, file No. E64380  
Approved by VDE, No.5922UG

## ■ Applications

1. Programmable controllers

## ■ Package Specifications

Model No.	Taping specifications
<b>PC3H4</b>	Taping reel diameter 330mm (3 000pcs.)
<b>PC3Q64Q</b>	Taping reel diameter 330mm (1 000pcs.)

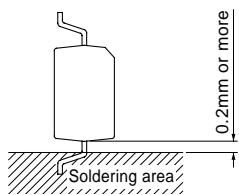
## ■ Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	±50	mA
	* <sup>1</sup> Peak forward current	I <sub>FM</sub>	±1	A
Output	Power dissipation	P	70	mW
	Collector-emitter voltage	V <sub>CEO</sub>	70	V
	PC3H4	V <sub>CEO</sub>	35	V
	PC3Q64Q	V <sub>CEO</sub>	6	V
	Emitter-collector voltage	V <sub>ECO</sub>	6	V
	Collector current	I <sub>C</sub>	50	mA
	Collector power dissipation	P <sub>C</sub>	150	mW
	Total power dissipation	P <sub>tot</sub>	170	mW
	* <sup>2</sup> Isolation voltage	V <sub>iso</sub>	2.5	kVrms
	Operating temperature	T <sub>opr</sub>	-30 to +100	°C
	Storage temperature	T <sub>stg</sub>	-40 to +125	°C
	* <sup>3</sup> Soldering temperature	T <sub>sol</sub>	260	°C

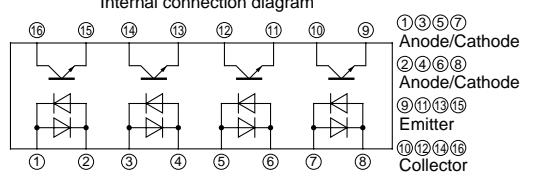
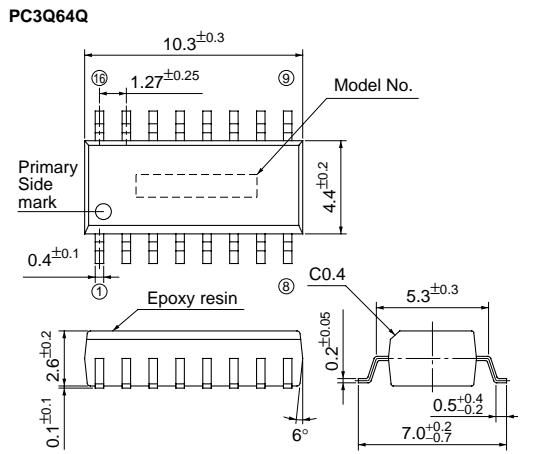
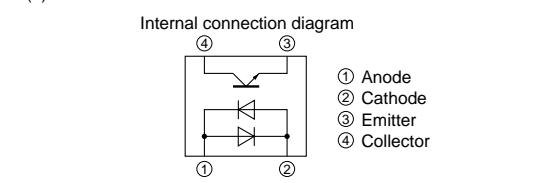
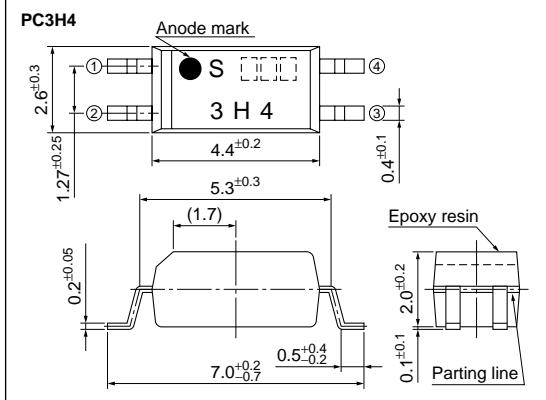
\*1 Pulse width<100μs, Duty ratio : 0.001

\*2 AC for 1min, 40 to 60%RH, f=60Hz

\*3 For 10s



## ■ Outline Dimensions (Unit : mm)

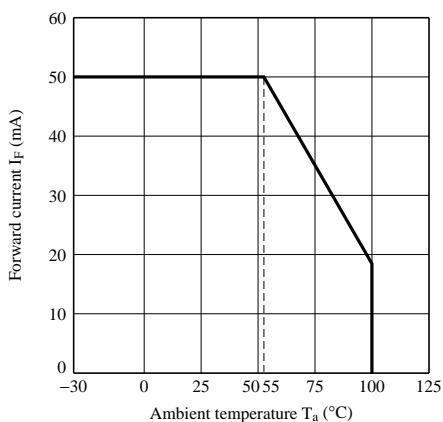


## ■ Electro-optical Characteristics

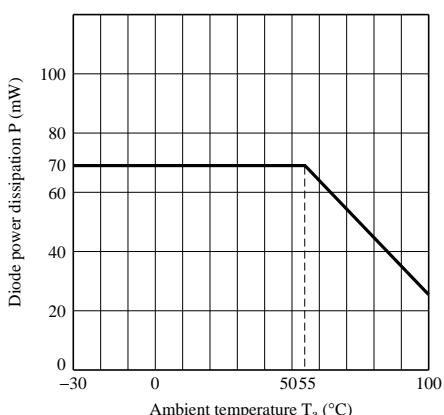
(Ta=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V <sub>F</sub>	I <sub>F</sub> =±20mA	—	1.2	1.4	V
	Terminal capacitance	C <sub>t</sub>	V=0, f=1kHz	—	30	250	pF
Output	Collector dark current <b>PC3H4</b>	I <sub>CEO</sub>	V <sub>CE</sub> =50V, I <sub>F</sub> =0	—	—	100	nA
	<b>PC3Q64Q</b>	I <sub>CEO</sub>	V <sub>CE</sub> =20V, I <sub>F</sub> =0	—	—	100	nA
	Collector-emitter breakdown voltage <b>PC3H4</b>	BV <sub>CEO</sub>	I <sub>c</sub> =0.1mA, I <sub>F</sub> =0	70	—	—	V
	Collector-emitter breakdown voltage <b>PC3Q64Q</b>	BV <sub>CEO</sub>	I <sub>c</sub> =0.1mA, I <sub>F</sub> =0	35	—	—	V
Emitter-collector breakdown voltage		BV <sub>ECO</sub>	I <sub>E</sub> =10μA, I <sub>F</sub> =0	6	—	—	V
Transfer character- teristics	Collector current	I <sub>c</sub>	I <sub>F</sub> =±1mA V <sub>CE</sub> =5V	0.2	—	4.0	mA
	Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> =±20mA I <sub>c</sub> =1mA	—	0.1	0.2	V
	Isolation resistance	R <sub>ISO</sub>	DC500V 40 to 60%RH	5×10 <sup>10</sup>	1×10 <sup>11</sup>	—	Ω
	Floating capacitance	C <sub>f</sub>	V=0, f=1MHz	—	0.6	1.0	pF
	Response time	tr	V <sub>CE</sub> =2V I <sub>c</sub> =2mA R <sub>L</sub> =100Ω	—	4	18	μs
	Fall time	tf		—	3	18	μs

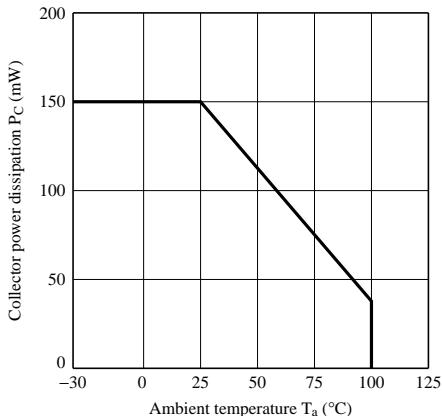
**Fig.1 Forward Current vs. Ambient Temperature**



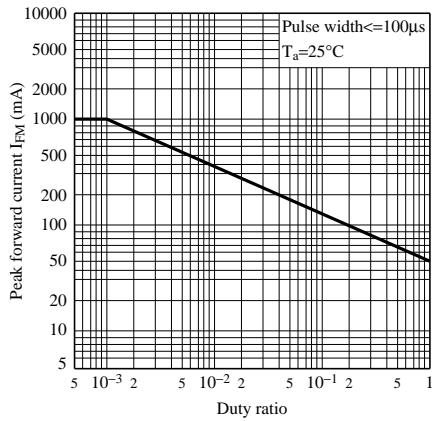
**Fig.2 Diode Power Dissipation vs. Ambient Temperature**



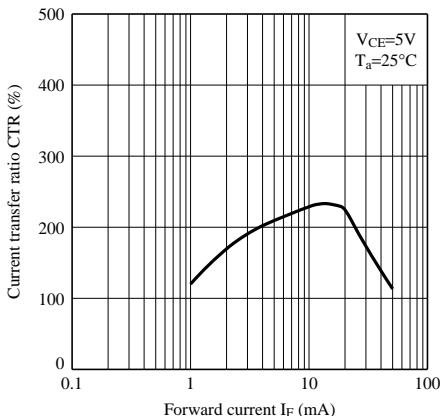
**Fig.3 Collector Power Dissipation vs. Ambient Temperature**



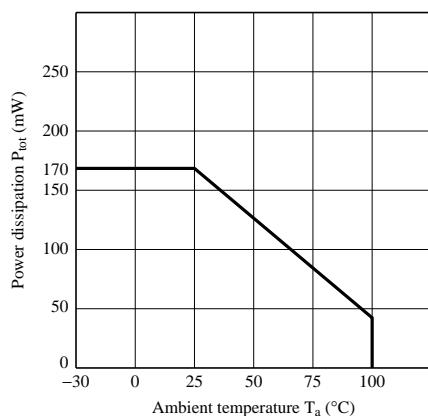
**Fig.5 Peak Forward Current vs. Duty Ratio**



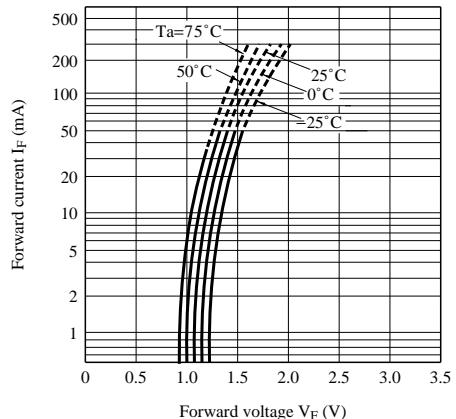
**Fig.7 Current Transfer Ratio vs. Forward Current**



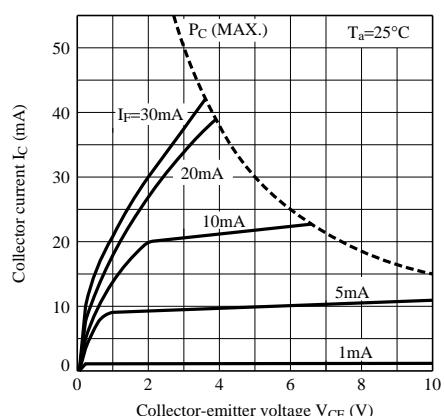
**Fig.4 Total Power Dissipation vs. Ambient Temperature**



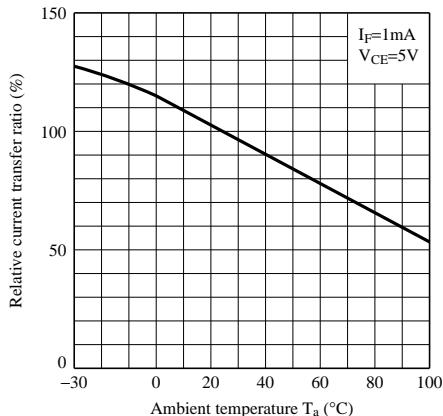
**Fig.6 Forward Current vs. Forward Voltage**



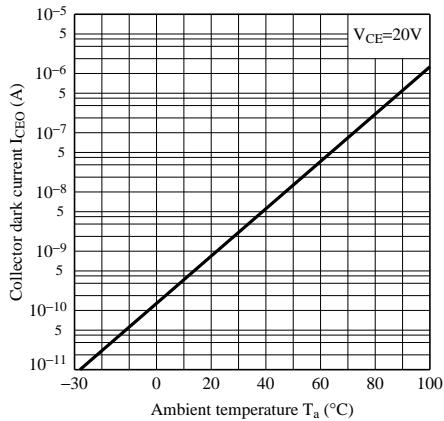
**Fig.8 Collector Current vs. Collector-emitter Voltage**



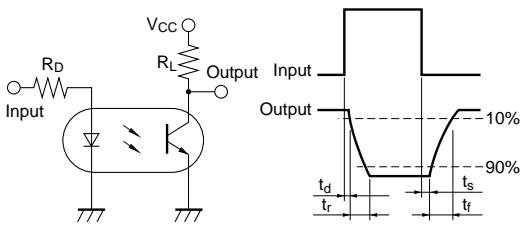
**Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature**



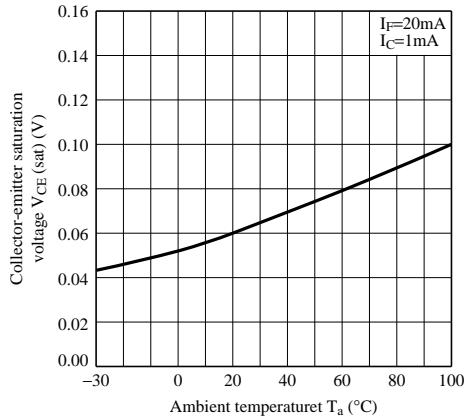
**Fig.11 Collector Dark Current vs. Ambient Temperature**



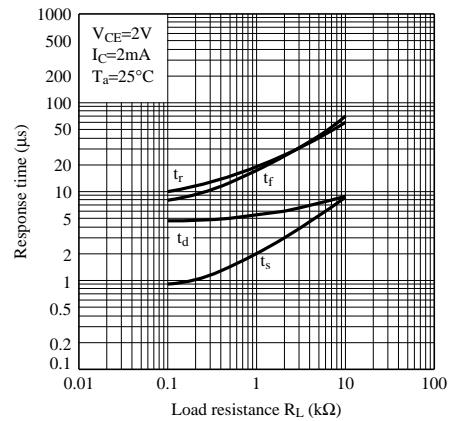
**Fig.13 Test Circuit For Response Time**



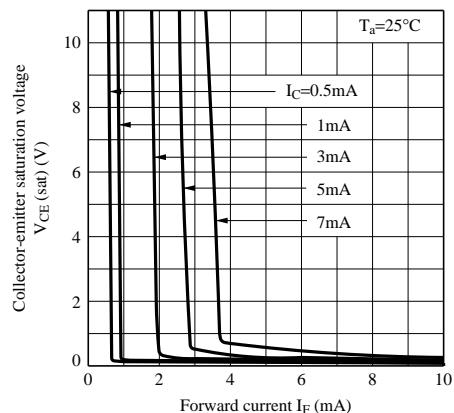
**Fig.10 Collector-emitter Saturation Voltage vs. Ambient Temperature**



**Fig.12 Response Time vs. Load Resistance**

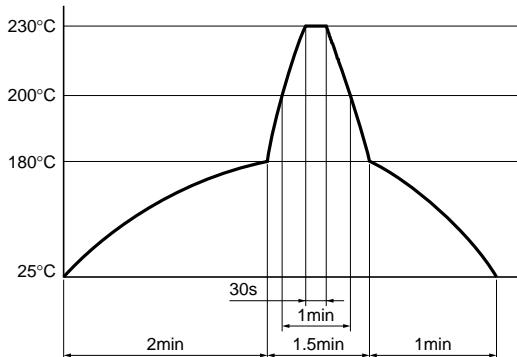


**Fig.14 Collector-emitter Saturation Voltage vs. Forward Current**



## Fig.5 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.



## ■ Precautions for Use

Please refer to the chapter "Precautions for Use".